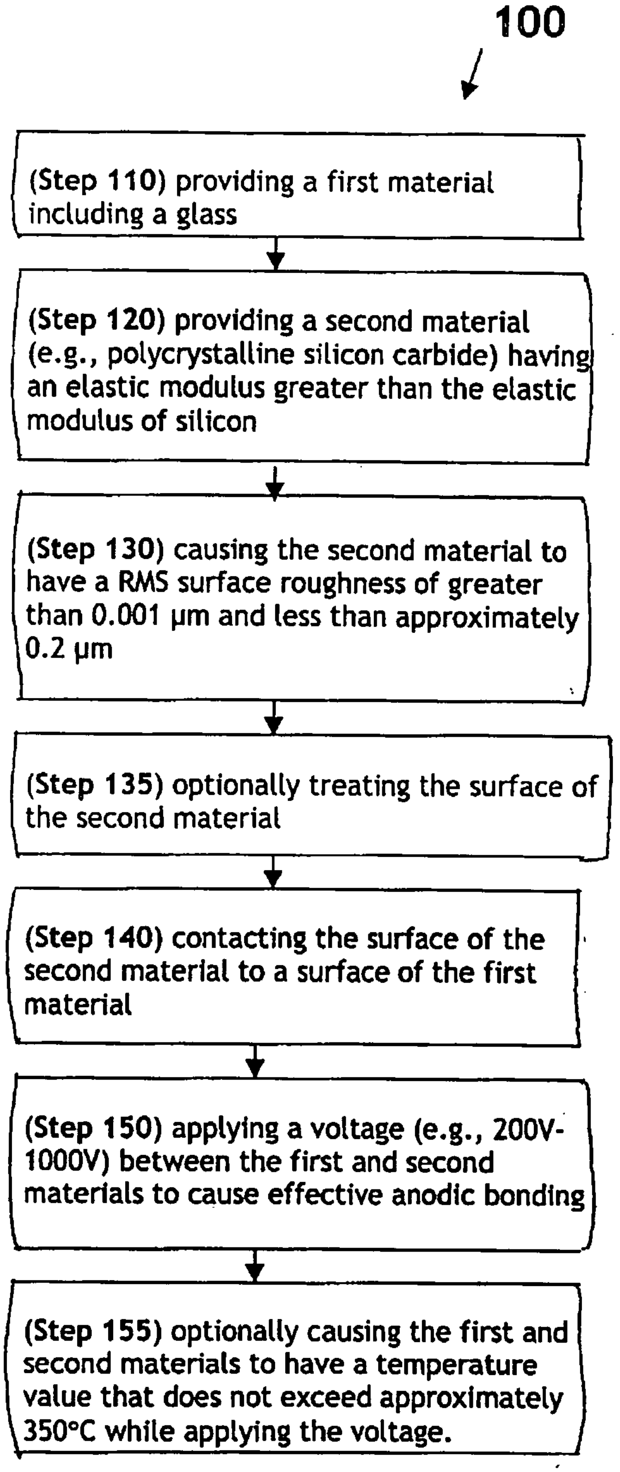

(Step 110) providing a first material including a glass

(Step 120) providing a second material (e.g., polycrystalline silicon carbide) having an elastic modulus greater than the elastic modulus of silicon

(Step 130) causing the second material to have a RMS surface roughness of greater than 0.001 μm and less than approximately 0.2 μm

(Step 135) optionally treating the surface of the second material

(Step 140) contacting the surface of the second material to a surface of the first material

(Step 150) applying a voltage (e.g., 200V-1000V) between the first and second materials to cause effective anodic bonding

(Step 155) optionally causing the first and second materials to have a temperature value that does not exceed approximately 350°C while applying the voltage.

FIG. 1

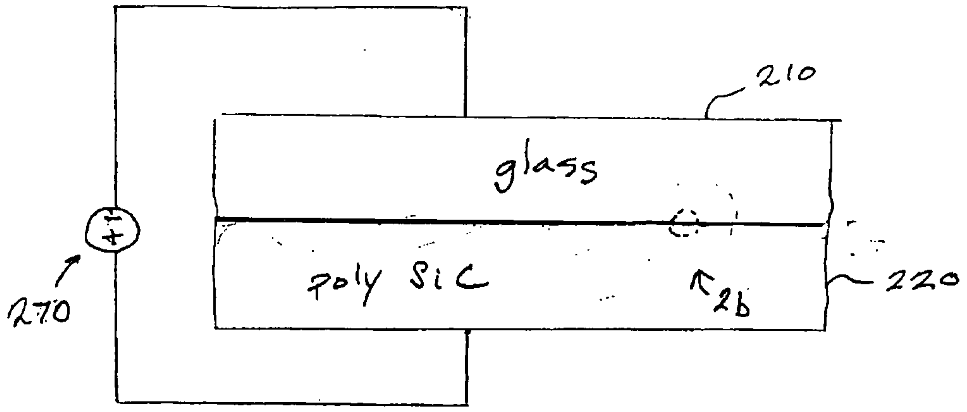

FIG. 2a

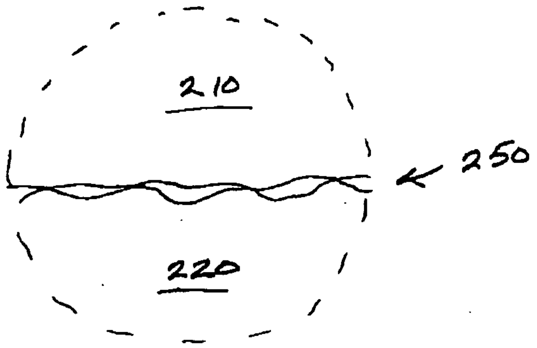

FIG. 2b

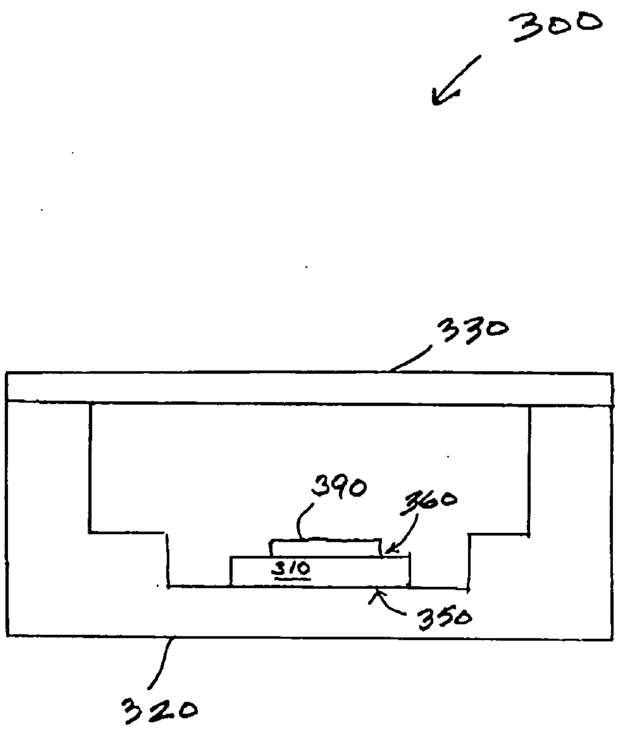

FIG.